

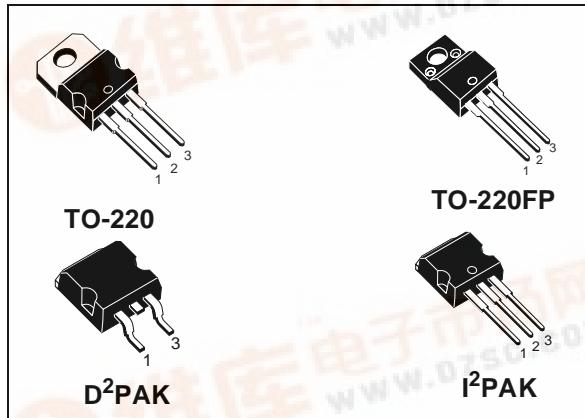


STP11NM60FD- STB11NM60FD STP11NM60FDFP - STB11NM60FD-1

N-CHANNEL 600V-0.40Ω-11ATO-220/TO-220FP/I²PAK/D²PAK
FDmesh™ Power MOSFET (with FAST DIODE)

TYPE	V _{DSS}	R _{D(on)}	I _D
STP11NM60FD	600 V	< 0.45Ω	11 A
STP11NM60FDFP	600 V	< 0.45Ω	11 A
STB11NM60FD	600 V	< 0.45Ω	11 A
STB11NM60FD-1	600 V	< 0.45Ω	11 A

- TYPICAL R_{D(on)} = 0.40Ω
- HIGH dv/dt AND AVALANCHE CAPABILITIES
- 100% AVALANCHE TESTED
- LOW INPUT CAPACITANCE AND GATE CHARGE
- LOW GATE INPUT RESISTANCE
- TIGHT PROCESS CONTROL AND HIGH MANUFACTURING YIELDS



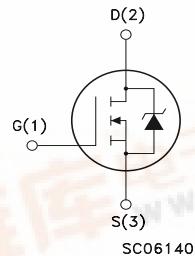
DESCRIPTION

The FDmesh™ associates all advantages of reduced on-resistance and fast switching with an intrinsic fast-recovery body diode. It is therefore strongly recommended for bridge topologies, in particular ZVS phase-shift converters.

APPLICATIONS

- ZVS PHASE-SHIFT FULL BRIDGE CONVERTERS FOR SMPS AND WELDING EQUIPMENT

INTERNAL SCHEMATIC DIAGRAM



ORDER CODES

PART NUMBER	MARKING	PACKAGE	PACKAGING
STP11NM60FD	P11NM60FD	TO-220	TUBE
STP11NM60FDFP	P11NM60FDFP	TO-220FP	TUBE
STB11NM60FDT4	B11NM60FD	D ² PAK	TAPE & REEL
STB11NM60FD-1	B11NM60FD	I ² PAK	TUBE

STP11NM60FD - STP11NM60FDFP - STB11NM60FD - STB11NM60FD-1

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		STP11NM60FD STB11NM60FD STB11NM60FD-1	STP11NM60FDFP	
V_{DS}	Drain-source Voltage ($V_{GS} = 0$)	600		V
V_{DGR}	Drain-gate Voltage ($R_{GS} = 20 \text{ k}\Omega$)	600		V
V_{GS}	Gate- source Voltage	± 30		V
I_D	Drain Current (continuos) at $T_C = 25^\circ\text{C}$	11	11 (*)	A
I_D	Drain Current (continuos) at $T_C = 100^\circ\text{C}$	7	7 (*)	A
$I_{DM} (\bullet)$	Drain Current (pulsed)	44	44 (*)	A
P_{TOT}	Total Dissipation at $T_C = 25^\circ\text{C}$	160	35	W
	Derating Factor	0.88	0.28	W/ $^\circ\text{C}$
dv/dt (1)	Peak Diode Recovery voltage slope	20		V/ns
V_{ISO}	Insulation Winthstand Voltage (DC)	--	2500	V
T_{stg}	Storage Temperature	−65 to 150		$^\circ\text{C}$
T_j	Max. Operating Junction Temperature			

(•)Pulse width limited by safe operating area

(1) $I_{SD} < 11\text{ A}$, $dI/dt < 400\text{ A}/\mu\text{s}$, $V_{DD} < V_{(BR)DSS}$, $T_J < T_{JMAX}$

(*)Limited only by maximum temperature allowed

THERMAL DATA

		TO-220/I ² PAK D ² PAK	TO-220FP	
$R_{thj-case}$	Thermal Resistance Junction-case	Max	0.78	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal Resistance Junction-ambient	Max	62.5	$^\circ\text{C/W}$
T_I	Maximum Lead Temperature For Soldering Purpose		300	$^\circ\text{C}$

AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I_{AR}	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T_j max)	5.5	A
E_{AS}	Single Pulse Avalanche Energy (starting $T_j = 25^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 35\text{ V}$)	350	mJ

ELECTRICAL CHARACTERISTICS ($T_{CASE} = 25^\circ\text{C}$ UNLESS OTHERWISE SPECIFIED) ON/OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$, $V_{GS} = 0$	600			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating}$, $T_C = 125^\circ\text{C}$			1 100	μA μA
I_{GSS}	Gate-body Leakage Current ($V_{DS} = 0$)	$V_{GS} = \pm 30\text{V}$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS} = 10\text{V}$, $I_D = 5.5\text{ A}$		0.40	0.45	Ω

STP11NM60FD - STP11NM60FDFP - STB11NM60FD - STB11NM60FD-1

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g_f (1)	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$, $I_D = 5.5A$		5.2		S
C_{iss}	Input Capacitance	$V_{DS} = 25V$, $f = 1$ MHz, $V_{GS} = 0$		1000		pF
C_{oss}	Output Capacitance			208		pF
C_{rss}	Reverse Transfer Capacitance			28		pF
C_{oss} eq. (2)	Equivalent Output Capacitance	$V_{GS} = 0V$, $V_{DS} = 0V$ to 400V		100		pF
R_G	Gate Input Resistance	$f=1$ MHz Gate DC Bias = 0 Test Signal Level = 20mV Open Drain		3		Ω

Note: 1. Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %.

2. C_{oss} eq. is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 250V$, $I_D = 5.5A$		20		ns
t_r	Rise Time	$R_G = 4.7\Omega$, $V_{GS} = 10V$ (see test circuit, Figure 3)		16		ns
Q_g	Total Gate Charge	$V_{DD} = 400V$, $I_D = 11A$,		28	40	nC
Q_{gs}	Gate-Source Charge	$V_{GS} = 10V$		7.8		nC
Q_{gd}	Gate-Drain Charge			13		nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(Voff)}$	Off-voltage Rise Time	$V_{DD} = 400V$, $I_D = 11A$,		10		ns
t_f	Fall Time	$R_G = 4.7\Omega$, $V_{GS} = 10V$		15		ns
t_c	Cross-over Time	(see test circuit, Figure 5)		24		ns

SOURCE DRAIN DIODE

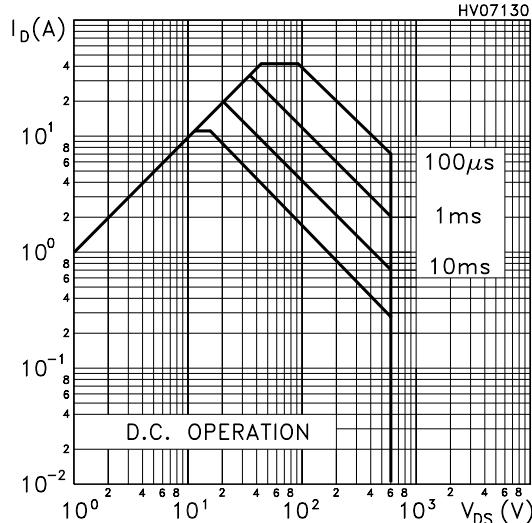
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain Current				11	A
I_{SDM} (2)	Source-drain Current (pulsed)				44	A
V_{SD} (1)	Forward On Voltage	$I_{SD} = 11A$, $V_{GS} = 0$			1.5	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 11A$, $di/dt = 100A/\mu s$,		190		ns
Q_{rr}	Reverse Recovery Charge	$V_{DD} = 50V$		1.1		μC
I_{RRM}	Reverse Recovery Current	(see test circuit, Figure 5)		14.5		A

Note: 1. Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %.

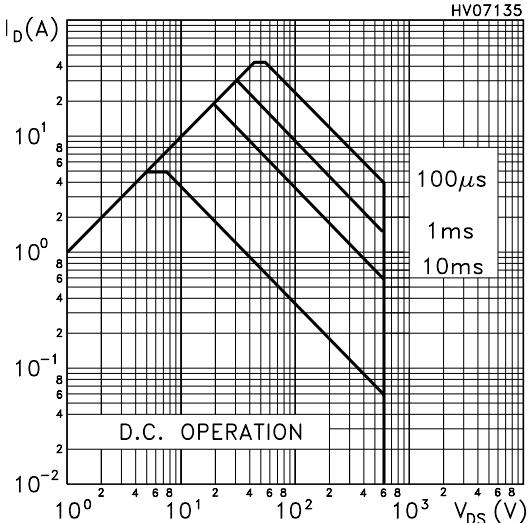
2. Pulse width limited by safe operating area.

STP11NM60FD - STP11NM60FDFP - STB11NM60FD - STB11NM60FD-1

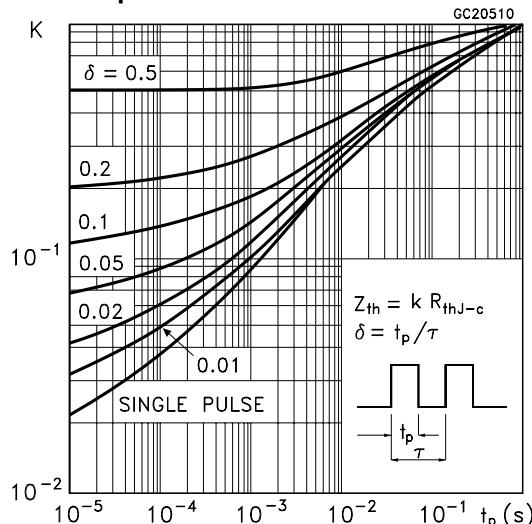
Safe Operating for TO-220/I²PAK/D²PAK



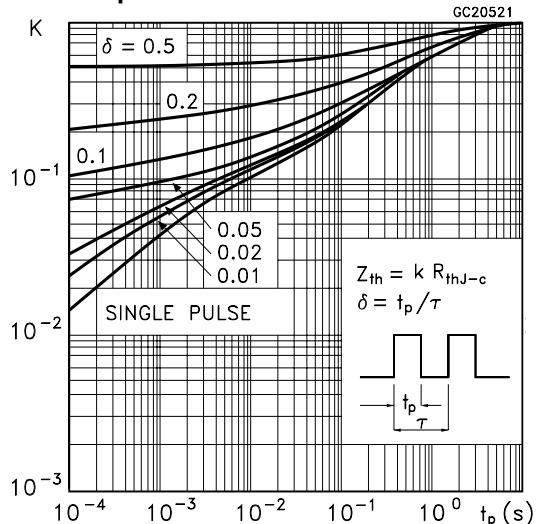
Safe Operating Area for TO-220FP



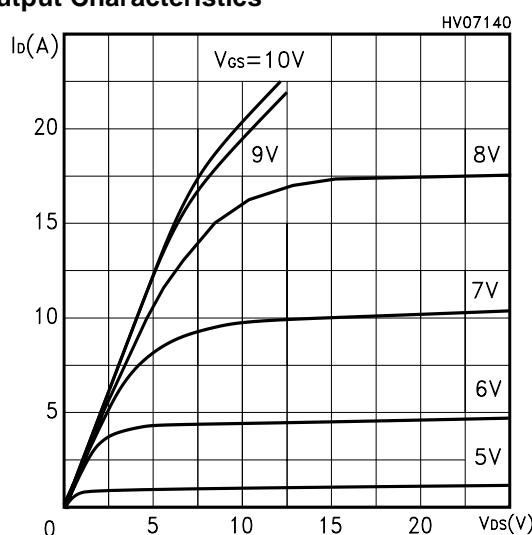
Thermal Impedance for TO-220/I²PAK



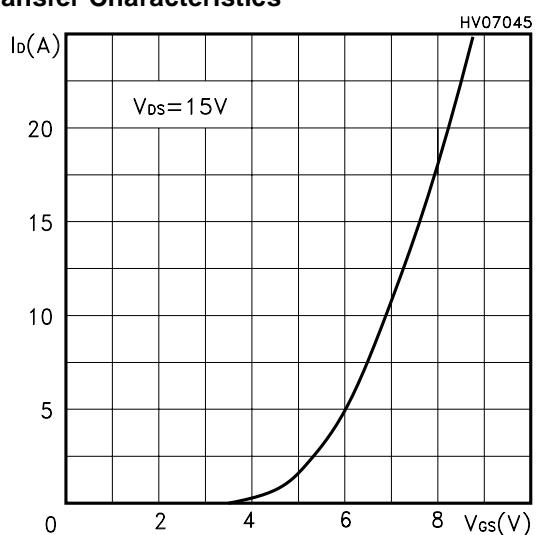
Thermal Impedance for TO-220FP



Output Characteristics

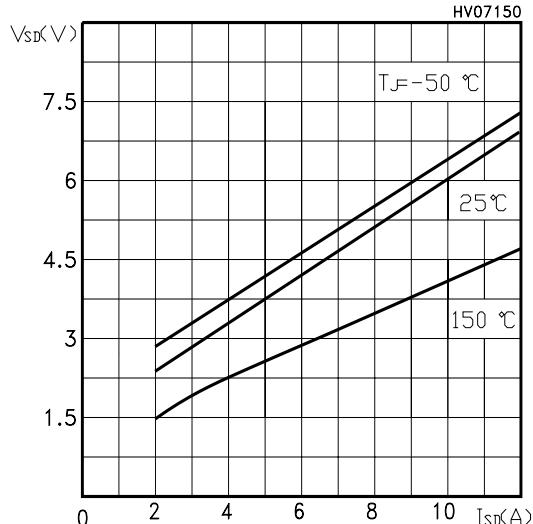


Transfer Characteristics

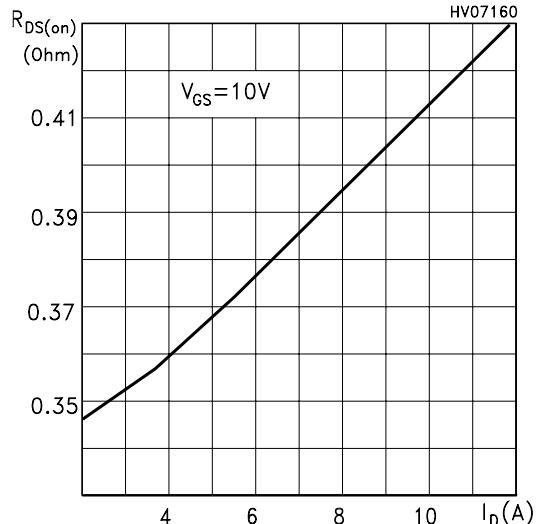


STP11NM60FD - STP11NM60FDFP - STB11NM60FD - STB11NM60FD-1

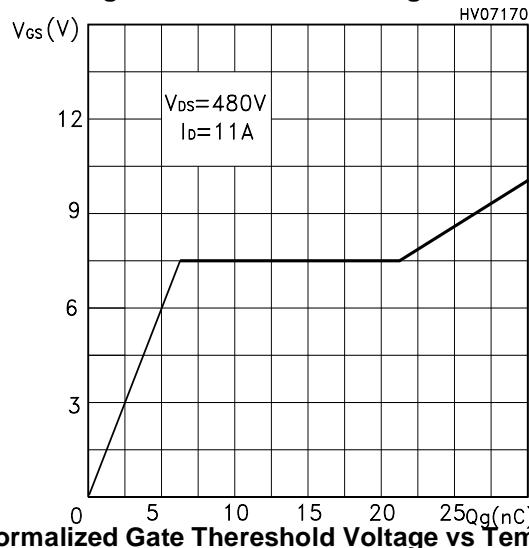
Transconductance



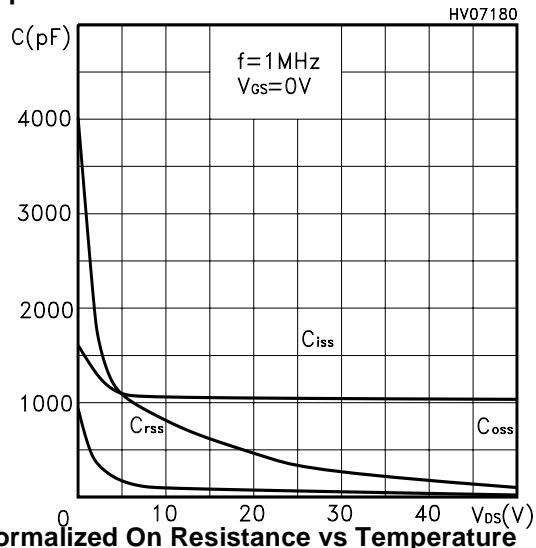
Static Drain-source On Resistance



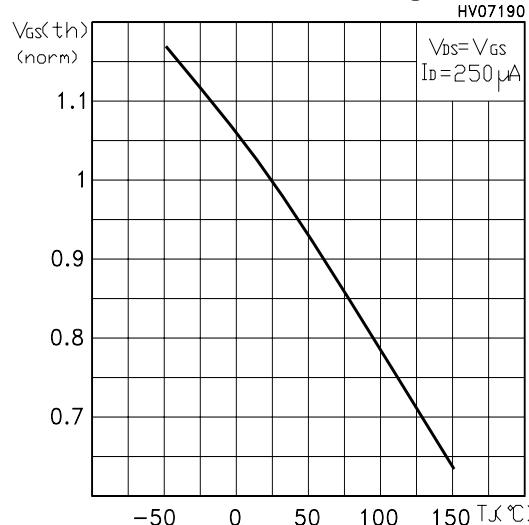
Gate Charge vs Gate-source Voltage



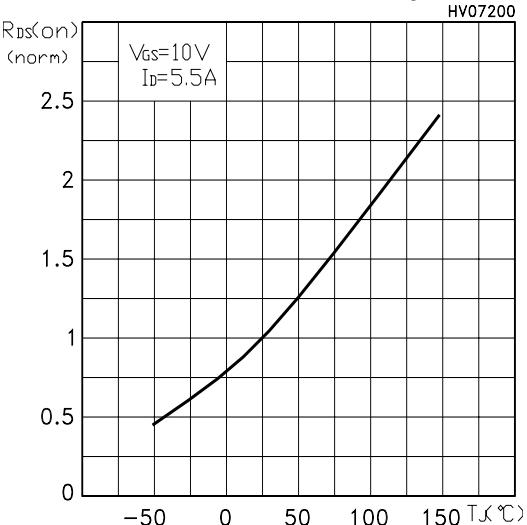
Capacitance Variations



Normalized Gate Threshold Voltage vs Temp.

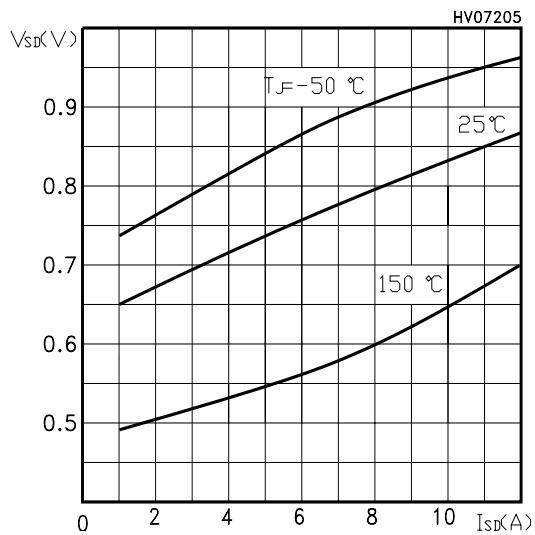


Normalized On Resistance vs Temperature



STP11NM60FD - STP11NM60FDFP - STB11NM60FD - STB11NM60FD-1

Source-drain Diode Forward Characteristics



STP11NM60FD - STP11NM60FDFP - STB11NM60FD - STB11NM60FD-1

Fig. 1: Unclamped Inductive Load Test Circuit

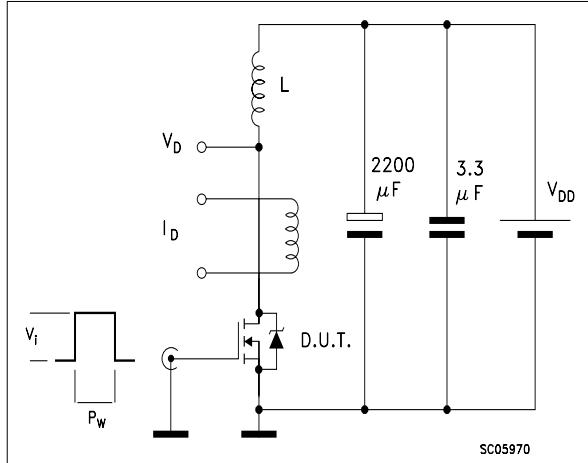


Fig. 2: Unclamped Inductive Waveform

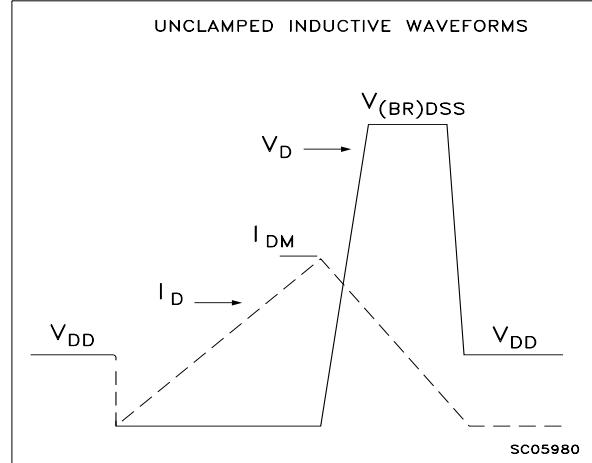


Fig. 3: Switching Times Test Circuit For Resistive Load

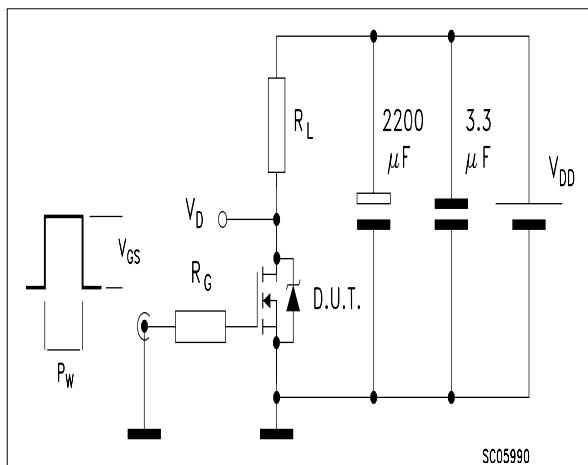


Fig. 4: Gate Charge test Circuit

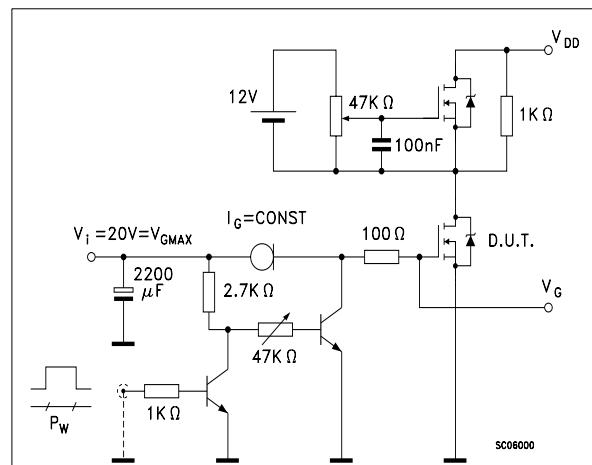
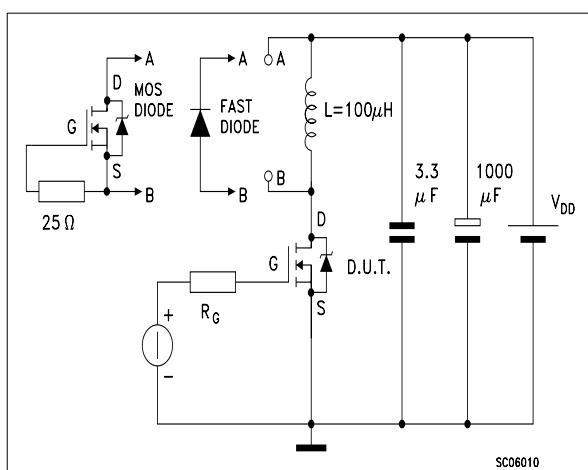


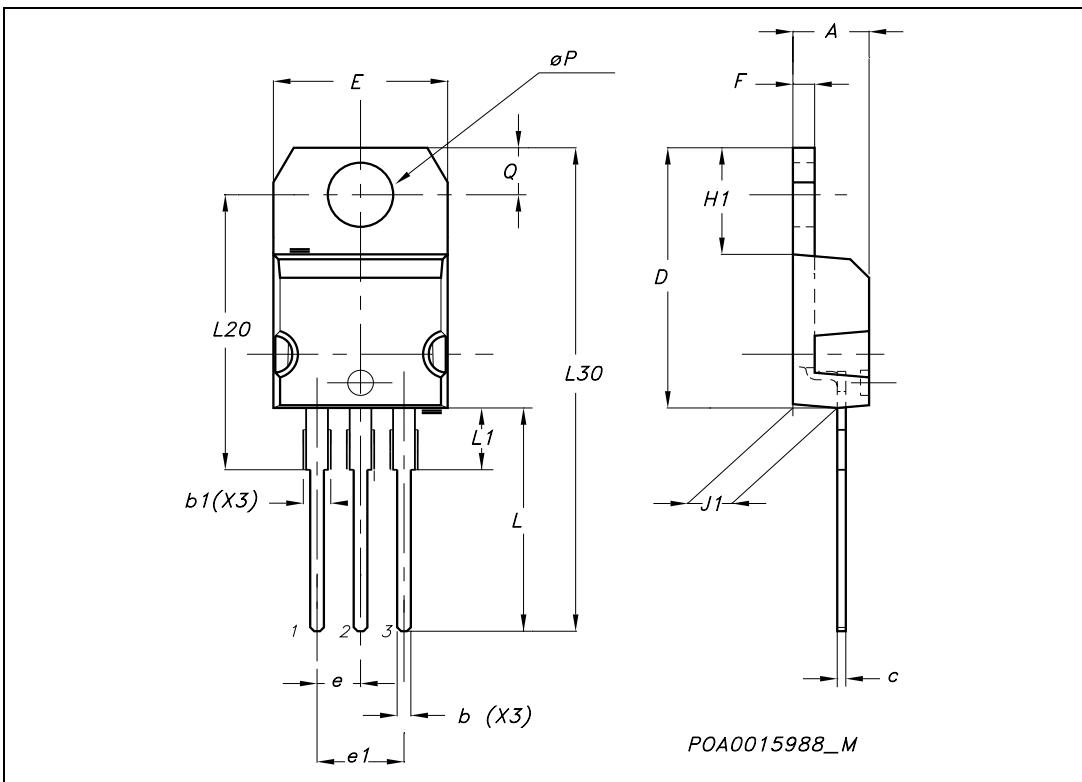
Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times



STP11NM60FD - STP11NM60FDFP - STB11NM60FD - STB11NM60FD-1

TO-220 MECHANICAL DATA

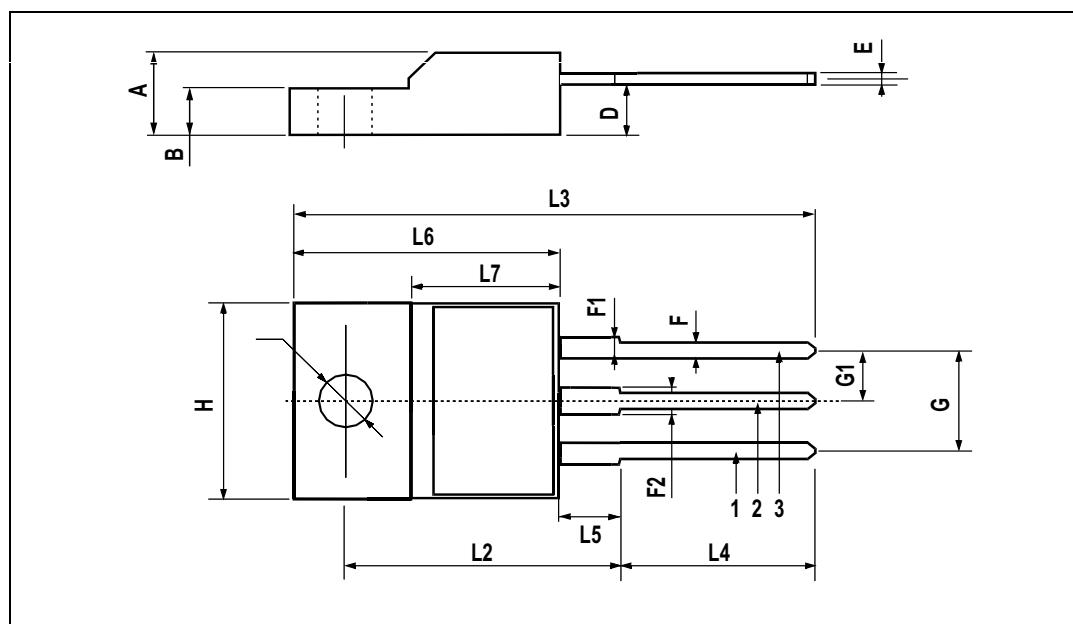
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
ϕP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



STP11NM60FD - STP11NM60FDFP - STB11NM60FD - STB11NM60FD-1

TO-220FP MECHANICAL DATA

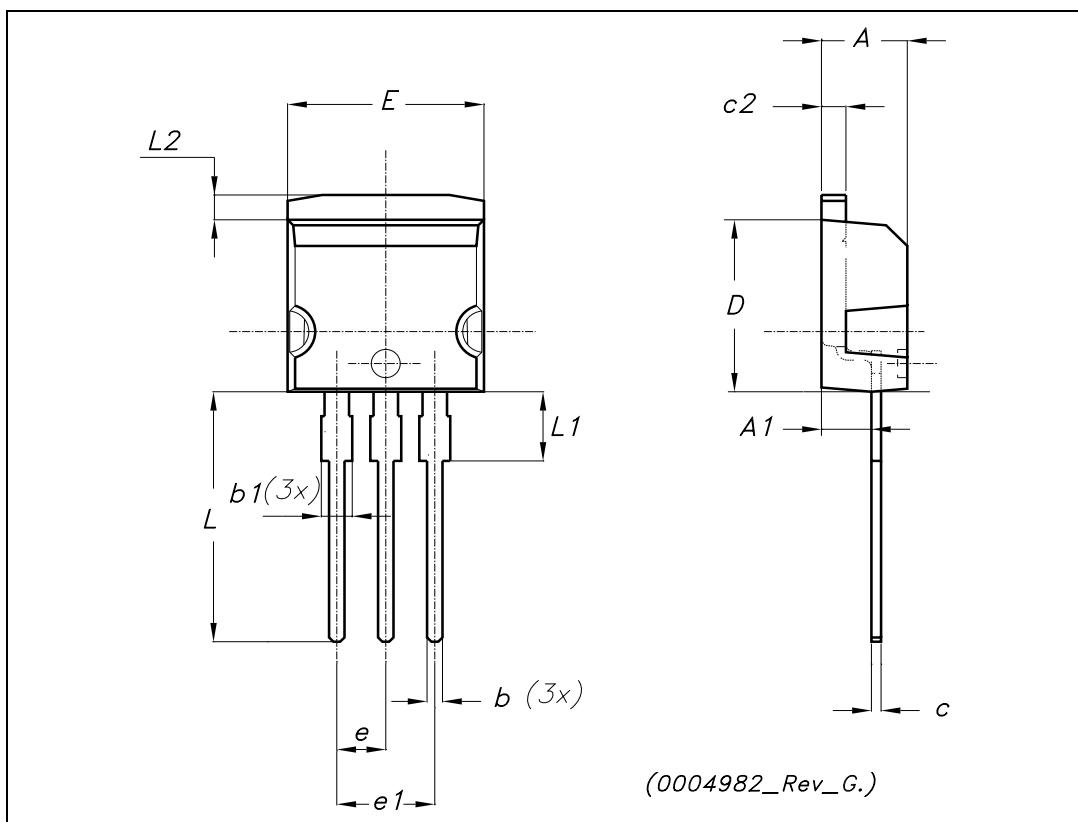
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	.0385		0.417
L5	2.9		3.6	0.114		0.141
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126



STP11NM60FD - STP11NM60FDFP - STB11NM60FD - STB11NM60FD-1

TO-262 (I²PAK) MECHANICAL DATA

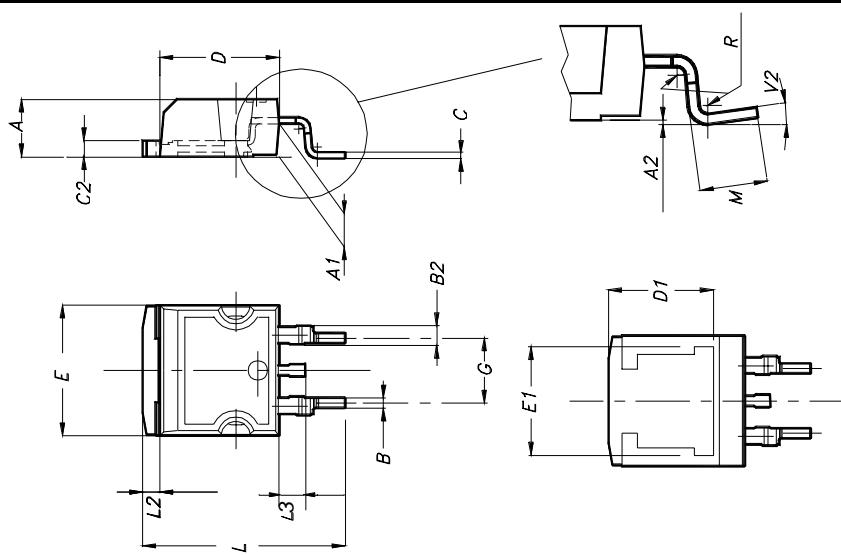
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
A1	2.40		2.72	0.094		0.107
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
c	0.49		0.70	0.019		0.027
c2	1.23		1.32	0.048		0.052
D	8.95		9.35	0.352		0.368
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
E	10		10.40	0.393		0.410
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L2	1.27		1.40	0.050		0.055



STP11NM60FD - STP11NM60FDFP - STB11NM60FD - STB11NM60FD-1

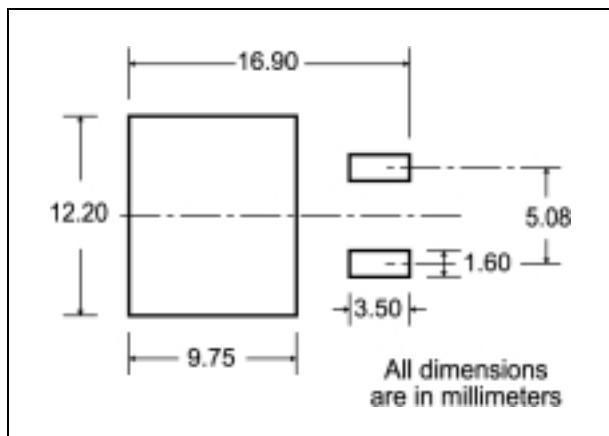
D²PAK MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
C	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1		8			0.315	
E	10		10.4	0.393		
E1		8.5			0.334	
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.625
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068
M	2.4		3.2	0.094		0.126
R		0.4			0.015	
V2	0°		4°			

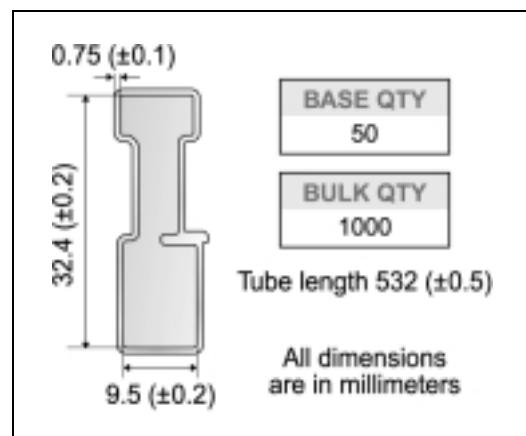


STP11NM60FD - STP11NM60FDFP - STB11NM60FD - STB11NM60FD-1

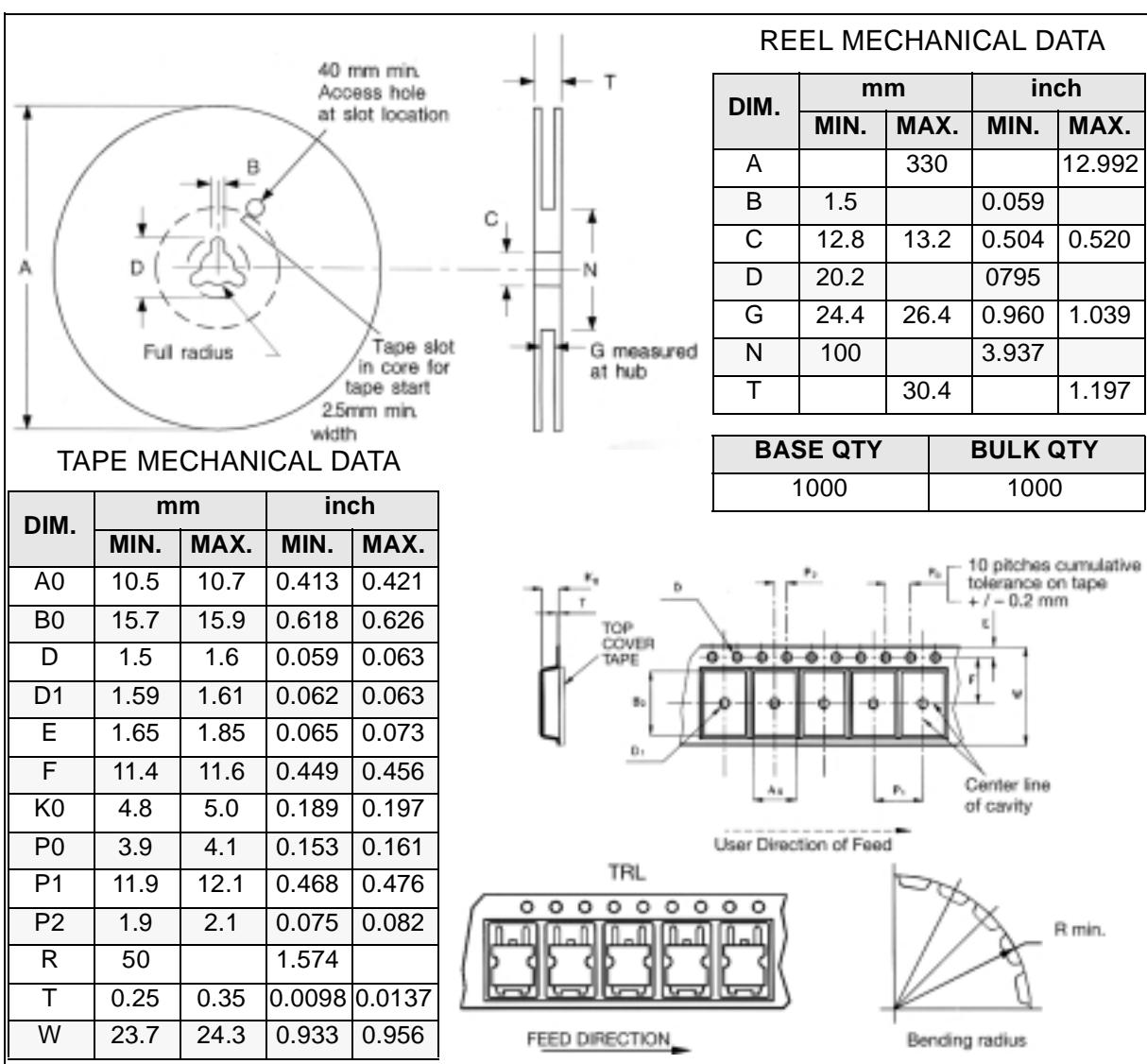
D²PAK FOOTPRINT



TUBE SHIPMENT (no suffix)*



TAPE AND REEL SHIPMENT (suffix "T4")*



* on sales type

12/13



STP11NM60FD - STP11NM60FDFP - STB11NM60FD - STB11NM60FD-1

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics
All other names are the property of their respective owners

© 2004 STMicroelectronics - All Rights Reserved
STMicroelectronics GROUP OF COMPANIES

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -
Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States.
<http://www.st.com>